



Product Change Notification

Change Notification #: 118359-01
Change Title: Select Intel® SSD 6 Series,
PCN 118359-01, Label,
Reason for Revision: Correct label Artwork
Label Update
Date of Publication: August 30, 2021

Key Characteristics of the Change:
Label

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	August 13, 2021
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Description of Change to the Customer:

Reason for Revision: Correct label Artwork

The Intel SKUs listed in the products affected table will have the following changes.

- 1) Update Custom label J47323-002 to J47323-003
- 2) Blank label change from NH J46300-003 to KH M11067-001 for all the above changes and logo: Caution Hot Surface (IEC 60471-5041) will be changed from black-white to yellow-black

Before



After



Customer Impact of Change and Recommended Action:

There is no change to the form, fit, or function of the product. The change is only to the labels used in packaging.

Customers should be aware of the changes to the label and take appropriate actions to accommodate the changes and avoid impact to their process.

Intel will attempt to deplete pre-conversion material before shipping post-conversion material but there is a possibility of Intel shipping mixed inventory. Therefore, customers will need to manage and migrate to the post-conversion material as soon as possible.

Milestone dates are estimates and subject to change based on business and operational conditions.

Products Affected/Intel Ordering Codes:

Marketing Name	Product Code	MM#
Intel® SSD 660p Series (2.0TB, M.2 80mm PCIe 3.0 x4, 3D2, QLC) Generic Single Pack	SSDPEKNW020T801	976804
Intel® SSD 660p Series (512GB, M.2 80mm PCIe 3.0 x4, 3D2, QLC) Retail Box Single Pack	SSDPEKNW512G8X1	978348
Intel® SSD 660p Series (512GB, M.2 80mm PCIe 3.0 x4, 3D2, QLC) Retail Box 10 Pack	SSDPEKNW512G8XT	978349
Intel® SSD 660p Series (1.0TB, M.2 80mm PCIe 3.0 x4, 3D2, QLC) Retail Box Single Pack	SSDPEKNW010T8X1	978350
Intel® SSD 660p Series (2.0TB, M.2 80mm PCIe 3.0 x4, 3D2, QLC) Retail Box Single Pack	SSDPEKNW020T8X1	978351
Intel® SSD 660p Series (2.0TB, M.2 80mm PCIe 3.0 x4, 3D2, QLC) Retail Box 10 Pack	SSDPEKNW020T8XT	984872
Intel® SSD 660p Series (1.0TB, M.2 80mm PCIe 3.0 x4, 3D2, QLC) Retail Box 10 Pack	SSDPEKNW010T8XT	984875
Intel® SSD 660p Series (512GB, M.2 80mm PCIe 3.0 x4, 3D2, QLC) Generic 100 Pack	SSDPEKNW512G8AS	999M0M
Intel® SSD 660p Series (1.0TB, M.2 80mm PCIe 3.0 x4, 3D2, QLC) Generic 100 Pack	SSDPEKNW010T8AS	999M0V
Intel® SSD 660p Series (512GB, M.2 80mm PCIe 3.0 x4, 3D2, QLC) Generic Single Pack	SSDPEKNW512G8AU	999M5F
Intel® SSD 660p Series (1.0TB, M.2 80mm PCIe 3.0 x4, 3D2, QLC) Generic Single Pack	SSDPEKNW010T8AU	999M5H

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
July 14, 2021	00	Originally Published PCN
August 30, 2021	01	Correct label Artwork



Product Change Notification

118359-01

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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